

ARCHIVE 2006 Welcome

BiTS 2006 Welcome Remarks

Fred Taber BiTS General Chairman

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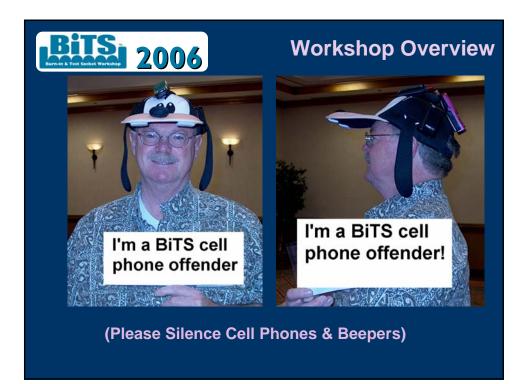


















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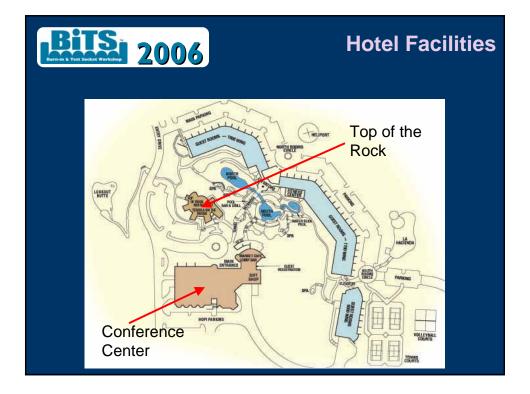
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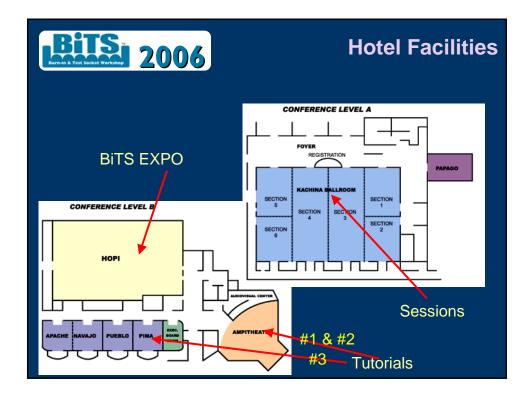














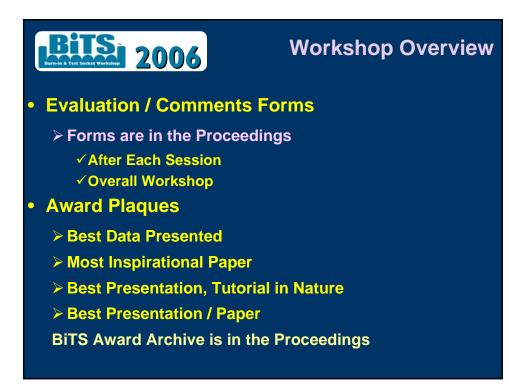








Workshop Overview Meet and Chat With Someone You Don't Know Many Opportunities to Network, Share & Discuss 3 Breakfasts, 2 Lunches, 3 Receptions and 2 Dinners Plus: Chef Stations with Monday Evening Reception During the EXPO Morning and Afternoon Breaks Networking Time on Monday and Tuesday Afternoon Monday Evening Social Event Casino Night: "BiTS – Deal Yourself A Winning Hand" BiTS EXPO Social Activities In Conjunction With the Exhibits











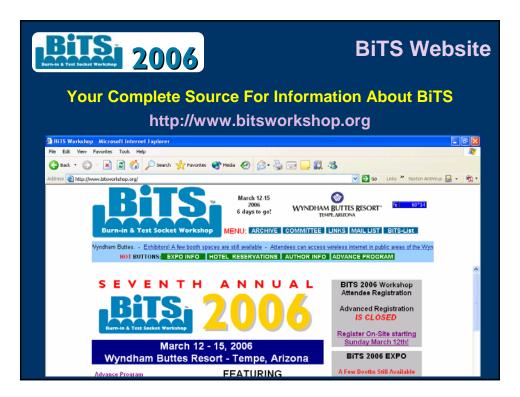


Special Award

The (Almost) Brilliant Disguise Award



BiTS 2005 – John Harkness – Brush Wellman BiTS 2004 – Helge Puhlmann – Yamaichi BiTS 2003 – Roger Weiss – Paricon Technologies BiTS 2002 - Mike Niederhofer & Bruce Simikowski - Incal BiTS 2001 - Jim Ostendorf - Dynavision BiTS 2000 - Mehdi Attaran - Oztek







Distantbitbitcomplete



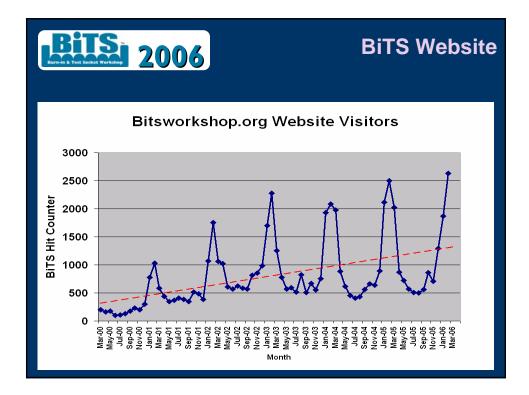


BiTS Website

Your Complete Source For Information About BiTS http://www.bitsworkshop.org

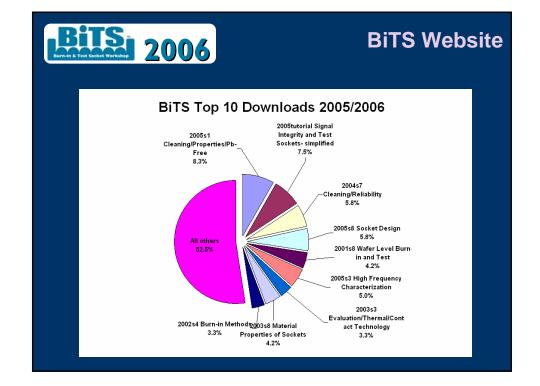
Coming Soon

BiTS 2006 Archive (April/May 2006) BiTS 2007 Call For Presentations (August 2006)









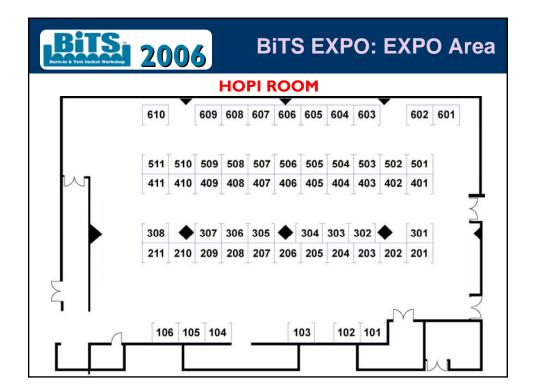


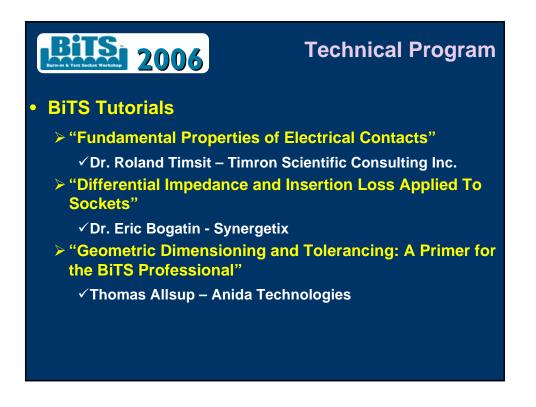




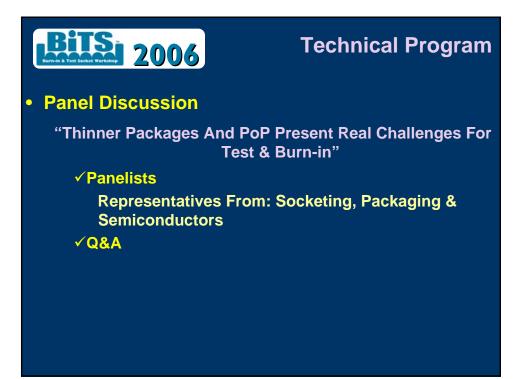
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101 102	ISU Petasys Corp. Aehr Test Systems	103 104	Kulicke & Soffa 3M	105 106	377
201 202 203 204	UMD Advanced Test Tech. UMD Advanced Test Tech. Rika Denshi America, Inc. Piper Plastics, Inc.	205 206 207 208	Custom Interconnects EDA Industries Synergetix Birk Manufacturing, Inc.	209 210 211	Azimuth Electronics, Inc. Hyperion Catalysis Int'l., Inc Everett Charles Tech.
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401 402 403 404	Yamaichi Electronics USA, Inc. Quadrant Eng. Plastic Prod. Gryphics, Inc. PPI-Time Zero Inc.	405 406 407 408	RS Tech, Inc. Brush Wellman, Inc. E. Jordan Brookes Co., Inc. Phoenix Test Arrays, LLC	409 410 411	,,
501 502 503	Johnstech International Corp. Electroworld Yokowo America Corporation	504 505 506	Chip Scale Review E-tec Interconnect, Ltd. RD Chemical Company	507 508 509	Nikon Instruments, Inc.
601 602 603 604	Paricon Technologies Corp. Marcel Electronics Int'l Ironwood Electronics NHK Spring Co., Ltd.	605 606	Digital Dimensions, Inc. / Solidworks Ardent Concepts, Inc.	607 608 609	Protos Electronics

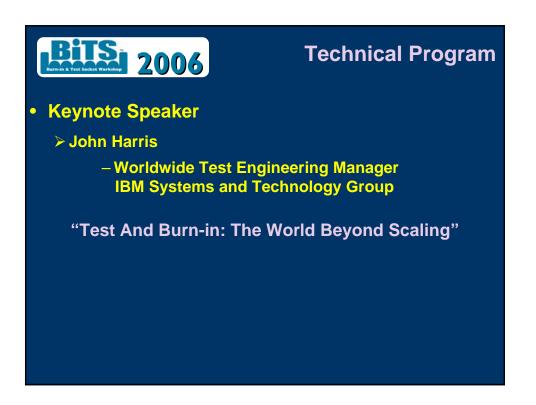














BITS 2006

Technical Program

9 Technical Sessions

- Advanced Socket Materials
- Socket Design And Performance
- Electrical Analysis And Characterization
- Managing Advanced Packaging Demands
- High Frequency Design And Measurement Considerations

- Interfacing: Contacting The Device And Beyond
- Hot Topics: A Trio Of Trends And Challenges
- Thermal Management Advances
- Test And Burn-in Efficiency Initiatives

AND

• 2 Supplemental Papers